THE INVENTION CLAIMED IS:

1. A method for fabricating a semiconductor heat spreader, comprising:

providing a unitary metallic plate; and

forming the unitary metallic plate into:

a panel;

channel walls depending from the panel to define a channel between the channel walls and the panel for receiving a semiconductor therein;

at least two feet extending from respective channel walls for attachment to a substrate; and

at least one external reversing bend.

2. The method of claim 1 wherein the feet are selected from an arched foot, a stand-off foot, a slotted stand-off foot, a toed foot, a stand-off toed foot, a flat foot, a slotted flat foot, a zigzag foot, a box foot, and a combination thereof.

3. The method of claim 1 further comprising forming the feet to accommodate respective set volumes of adhesive therebeneath for attaching the semiconductor heat spreader to a substrate.

4. The method of claim 1 further comprising forming an electromagnetic interference shield for the channel.

5. The method of claim 1 further comprising:

providing an additional unitary metallic plate; and

forming the additional unitary metallic plate into a unitary auxiliary heat spreader configured for attachment on top of the semiconductor heat spreader.

6. The method of claim 5 further comprising forming attachment means for attaching the unitary auxiliary heat spreader to the semiconductor heat spreader, the attachment means being selected from tabs, locking tabs, deformable sides, side ledges, side clips, clip bosses, center clips, side arms, and a combination thereof.

7. The method of claim 1 wherein forming the unitary metallic plate further comprises forming the unitary metallic plate in substantially a single metal forming process to also form an integral auxiliary heat spreader located on top of the panel.

8. The method of claim 1 wherein forming the unitary metallic plate further comprises forming the unitary metallic plate in substantially a single metal forming process into a cross-sectional profile that is substantially constant in at least one horizontal direction.

9. A method for fabricating a semiconductor heat spreader, comprising:

providing a unitary metallic plate;

forming the unitary metallic plate in substantially a single metal forming process into:

a panel;

channel walls depending from opposite sides of the panel to define a channel between the channel walls and the panel for receiving a semiconductor therein;

at least two feet extending from respective channel walls on opposite sides of the panel for attachment to a substrate, the feet being:

selected from an arched foot, a stand-off foot, a slotted stand-off foot, a toed foot, a stand-off toed foot, a flat foot, a slotted flat foot, a zigzag foot, a box foot, and a combination thereof; and

formed to accommodate respective set volumes of adhesive therebeneath for attaching the semiconductor heat spreader to a substrate;

a cross-sectional profile that is substantially constant in at least one horizontal direction; and

at least one external reversing bend.

10. The method of claim 9 further comprising:

providing an additional unitary metallic plate;

forming the additional unitary metallic plate in substantially a single metal forming process into a unitary auxiliary heat spreader configured for attachment on top of the semiconductor heat spreader; and

forming attachment means for attaching the unitary auxiliary heat spreader to the semiconductor heat spreader, the attachment means being selected from tabs, locking tabs, deformable sides, side ledges, side clips, clip bosses, center clips, side arms, and a combination thereof.

11. A semiconductor heat spreader comprising a unitary metallic plate having:

a panel;

channel walls depending from the panel to define a semiconductor receiving channel between the channel walls and the panel;

at least two feet extending from respective channel walls for attachment to a substrate; and

at least one external reversing bend.

12. The semiconductor heat spreader of claim 11 wherein the feet are selected from an arched foot, a stand-off foot, a slotted stand-off foot, a toed foot, a stand-off toed foot, a flat foot, a slotted flat foot, a zigzag foot, a box foot, and a combination thereof.

13. The semiconductor heat spreader of claim 11 wherein the feet are formed to accommodate respective set volumes of adhesive therebeneath for attaching the semiconductor heat spreader to a substrate.

14. The semiconductor heat spreader of claim 11 further comprising an electromagnetic interference shield for the channel.

15. The semiconductor heat spreader of claim 11 further comprising an additional unitary metallic plate configured as a unitary auxiliary heat spreader for attachment on top of the semiconductor heat spreader.

16. The semiconductor heat spreader of claim 15 further comprising attachment means for attaching the unitary auxiliary heat spreader to the semiconductor heat spreader, the attachment means being selected from tabs, locking tabs, deformable sides, side ledges, side clips, clip bosses, center clips, side arms, and a combination thereof.

17. The semiconductor heat spreader of claim 11 further comprising an integral auxiliary heat spreader formed from the unitary metallic plate, located on top of the panel, and having the physical characteristics of being formed in a unitary metal forming process.

18. The semiconductor heat spreader of claim 11 wherein the unitary metallic plate has the physical characteristics of being formed in a unitary metal forming process and a cross-sectional profile that is substantially constant in at least one horizontal direction.

19. A semiconductor heat spreader comprising a unitary metallic plate having:

a panel;

channel walls depending from opposite sides of the panel to define a semiconductor receiving channel between the channel walls and the panel;

at least two feet extending from respective channel walls on opposite sides of the panel for attachment to a substrate, the feet being:

selected from an arched foot, a stand-off foot, a slotted stand-off foot, a toed foot, a stand-off toed foot, a flat foot, a slotted flat foot, a zigzag foot, a box foot, and a combination thereof; and

formed to accommodate respective set volumes of adhesive therebeneath for attaching the semiconductor heat spreader to a substrate;

a cross-sectional profile that is substantially constant in at least one horizontal direction;

the physical characteristics of being formed in a unitary metal forming process; and

at least one external reversing bend.

20. The semiconductor heat spreader of claim 19 further comprising:

an additional unitary metallic plate configured as a unitary auxiliary heat spreader for attachment on top of the semiconductor heat spreader and having the physical characteristics of being formed in a unitary metal forming process; and

attachment means for attaching the unitary auxiliary heat spreader to the semiconductor heat spreader, the attachment means being selected from tabs, locking tabs, deformable sides, side ledges, side clips, clip bosses, center clips, side arms, and a combination thereof.